



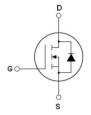
# N-Channel Super Junction Power MOSFET II

### **General Description**

The series of devices use advanced super junction technology and design to provide excellent R<sub>DS(ON)</sub> with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

#### **Features**

- ◆ New technology for high voltage device
- ◆ Low on-resistance and low conduction losses
- ◆ Small package
- ◆ Ultra Low Gate Charge cause lower driving requirements
- ◆ 100% Avalanche Tested
- ◆ ROHS compliant





Schematic diagram

TO-251

### **Application**

- ◆ Power factor correction (PFC)
- Switched mode power supplies (SMPS)
- ◆ Uninterruptible Power Supply (UPS)

VDS@Tjmax	650	V
RDS(ON) TYP	1.85	Ω
lσ	2	А

### Package Marking And Ordering Information

Device	Device Device Package	
MJ60R2K2I	TO-251	MJ60R2K2I

### Table 1. Absolute Maximum Ratings (Tc=25℃)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (Vcs=0V)	VDS	600	V
Gate-Source Voltage (Vps=0V)	Vgs	±30	V
Continuous Drain Current at Tc=25°C	ID (DC)	2	А
Continuous Drain Current at Tc=100°C	ID (DC)	1.3	А
Pulsed drain current (Note 1)	IDM (pluse)	6	А
Maximum Power Dissipation (Tc=25°C)	Po	23	W
Derate above 25°C	Po	0.184	W/°C
Single pulse avalanche energy (Note 2)	Eas	45	mJ
Avalanche current (Note 1)	lar	1	А
Repetitive Avalanche energy, tar limited by T <sub>jmax</sub> (Note 1)	Ear	0.06	mJ

Parameter	Symbol	Value	Unit
Drain Source voltage slope, V <sub>DS</sub> ≤480 V	dv/dt	50	V/ns
Reverse diode dv/dt, V <sub>DS</sub> ≤480 V,I <sub>SD</sub> <i<sub>D</i<sub>	dv/dt	15	V/ns
Operating Junction and Storage Temperature Range	TJ,Tsтg	-55+150	°C





### Table 2. Thermal Characteristic

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	RthJC	5.4	°C/W
Thermal Resistance, Junction-to-Ambient (Maximum)	RthJA	75	°C/W

## Table 3. Electrical Characteristics (T<sub>A</sub>=25℃ unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit	
On/off states							
Drain-Source Breakdown Voltage	BVDSS	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	600	-	_	V	
Zero Gate Voltage Drain Current (Tc=25°C)	loss	V <sub>DS</sub> =600V,V <sub>GS</sub> =0V	-	-	1	μΑ	
Zero Gate Voltage Drain Current (Tc=125°C)	loss	V <sub>DS</sub> =600V,V <sub>GS</sub> =0V	-	-	10	μA	
Gate-Body Leakage Current	lgss	V <sub>GS</sub> =±30V,V <sub>DS</sub> =0V	-	-	±100	nA	
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250μA	2.5	3	3.5	V	
Drain-Source On-State Resistance	Rds(on)	V <sub>G</sub> s=10V,I <sub>D</sub> =1A	-	1850	2200	mΩ	
Dynamic Characteristics	'						
Forward Transconductance	grs	V <sub>DS</sub> =20V,I <sub>D</sub> =1A	-	2	_	S	
Input Capacitance	Cies		-	190	-	PF	
Output Capacitance	Coss	V <sub>DS</sub> =50V,V <sub>GS</sub> =0V F=1.0MHz	-	13	-	PF	
Reverse Transfer Capacitance	Crss	-	-	1.1	-	PF	
Total Gate Charge	Qg		-	3.2	10	nC	
Gate-Source Charge	Qgs	V <sub>DS</sub> =480V,I <sub>D</sub> =2A V <sub>GS</sub> =10V	-	0.6	-	nC	
Gate-Drain Charge	Qgd		-	1.2	-	nC	
Intrinsic gate resistance	Rg	f=1 MHz open drain	-	9	-	Ω	
Switching times				1			
Turn-on Delay Time	t <sub>d(on)</sub>		-	6	_	nS	
Turn-on Rise Time	tr	V <sub>DD</sub> =380V,I <sub>D</sub> =1A	-	3	-	nS	
Turn-Off Delay Time	t <sub>d(off)</sub>	R <sub>G</sub> =50Ω,V <sub>GS</sub> =10V	-	65	-	nS	
Turn-Off Fall Time	tr	-	-	11	-	nS	
Source- Drain Diode Characteristics							
Source-drain current (Body Diode)	Isp		-	-	2	А	
Pulsed Source-drain current (Body Diode)	Isdm	- Tc=25°C	-	-	6	А	
Forward On Voltage	Vsp	T <sub>j</sub> =25°C,I <sub>SD</sub> =2A,V <sub>GS</sub> =0V	-	1	1.3	V	
Reverse Recovery Time	trr		-	140	-	nS	
Reverse Recovery Charge	Qrr	Tj=25°C,I⊧=2A di/dt=100A/µs	-	0.65	-	uC	
Peak reverse recovery current	Irrm	-	_	9	_	А	





ldr, Reverse Drain Current(A)

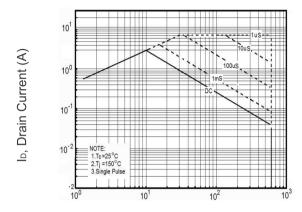
lb, Drain Current (A)

R<sub>DS(ON)</sub>, Drain-Source On-Resistance(Ω)

### Notes

- 1.Repetitive Rating: Pulse width limited by maximum junction temperature
- $2.T_j = 25^{\circ}C, V_{DD} = 50V, V_{G} = 10V, R_{G} = 25\Omega$

### TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)



V<sub>DS</sub>, Drain-Source Voltage (V)

Figure 1 Safe operating area

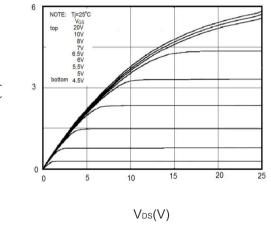


Figure 3 Output characteristics

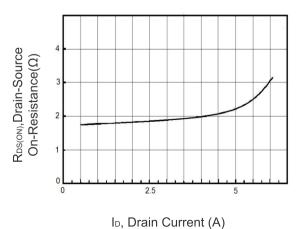
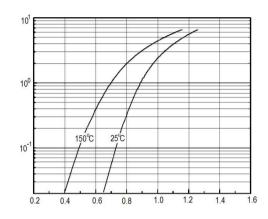
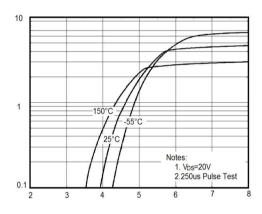


Figure 5 Static drain-source on resistance



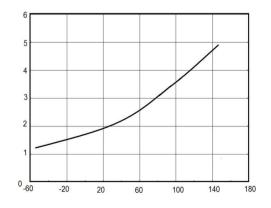
V<sub>SD</sub>,Source-Drain Voltage(V)

Figure 2 Source-Drain Diode Forward Voltage



V<sub>GS</sub>, Gate-Source Voltage (V)

Figure 4 Transfer characteristics



T<sub>J</sub>, Junction Temperature (°C)

Figure 6 Rds(ON) vs Junction Temperature

lo, Drain Current (A)

Capacitances(pF)



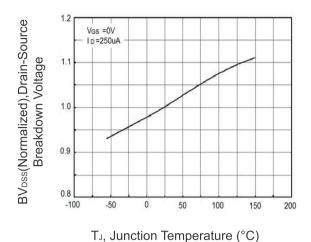
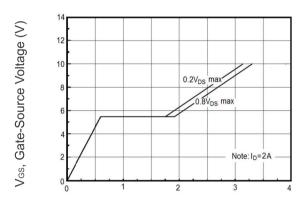
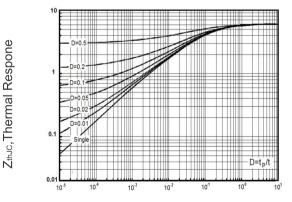


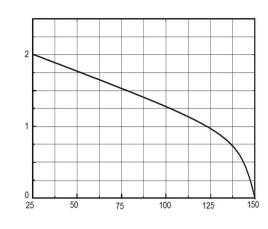
Figure 7 BVDSS vs Junction Temperature



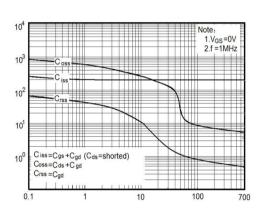
Q<sub>G</sub>,Total Gate Charge(nC) Figure 9 Gate charge waveforms



t₅,Square Wave Pulse(S) Figure 11 Transient Thermal Impedance



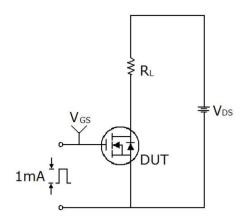
Tc, Case Temperature (°C) Figure 8 Maximum ID vs Junction Temperature

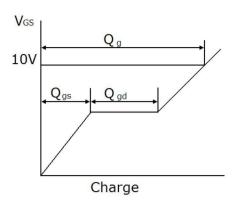


V<sub>DS</sub>, Drain-Source Voltage (V) Figure 10 Capacitance

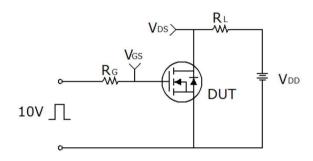


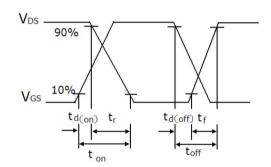
### Test circuit



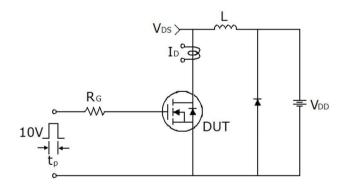


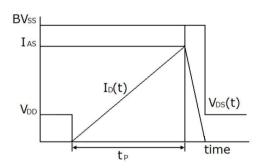
Gate charge test circuit & Waveform





Switch Time Test Circuit



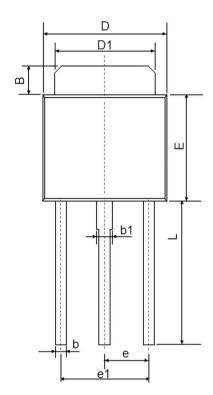


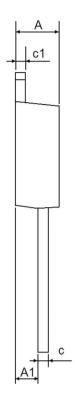
Unclamped Inductive Switching Test Circuit & Waveforms





## TO-251 Package Information





Comple at	Dimensions In Millimeters		Dimension	s In Inches
Symbol	Min.	Max.	Min.	Max.
А	2.200	2.400	0.087	0.094
A1	1.050	1.350	0.042	0.054
В	1.350	1.650	0.053	0.065
b	0.500	0.700	0.020	0.028
b1	0.700	0.900	0.028	0.035
С	0.430	0.580	0.017	0.023
c1	0.430	0.580	0.017	0.023
D	6.350	6.650	0.250	0.262
D1	5.200	5.400	0.205	0.213
E	5.400	5.700	0.213	0.224
е	2.300	2.300 TYP.		TYP.
e1	4.500	4.700	0.177	0.185
L	7.500	7.900	0.295	0.311





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